

REMARKS

This is in response to the Office Action dated December 8, 2005. Claims 1-13 are pending in this application.

Claim 1 stands rejected under 35 U.S.C. Section 102(e) as being allegedly anticipated by Chittipeddi. This Section 102(e) rejection is respectfully traversed for at least the following reasons.

Claim 1 require that “said second wiring layer includes a plurality of wirings formed in the region under said bonding pad, a predetermined wiring of said plurality of wirings is electrically connected to said bonding pad, and an insulating film is provided for insulating said bonding pad from other wirings than the predetermined wiring among said plurality of wirings, wherein said insulating film is formed *over* said other wirings so as to directly contact the bonding pad; said other wirings provided parallel to the edges of said bonding pad are not formed in regions right under the edges; and said insulating film is made up of an inorganic insulating film only, so that no organic insulating film is provided between the other wirings and the bonding pad.” For example and without limitation, Fig. 6 of the instant application illustrates that the insulating film 5 is provided for insulating bonding pad 1 from other wirings 12 than the predetermined wiring 6 among said plurality of wirings 2, and that the insulating film 5 is formed over (or above) said other wirings 12 so as to directly contact the bonding pad 1.

Chittipeddi (US 6,838,769) fails to disclose or suggest the aforesaid underlined features of claim 1. In particular, in Fig. 2 of Chittipeddi, the alleged insulating film 11 is not located “over” the alleged other wirings 19. In other words, the alleged insulating film 11 in Fig. 2 of Chittipeddi is not located between the alleged pad 17 and the alleged other wirings 19 in an area above the other wirings 19. Additionally, Chittipeddi’s insulating film 3 is not provided for

insulating the alleged bonding pad 17 from the other wirings 19 as required by claim 1.

Chittipeddi is entirely unrelated to the invention of claim 1 for each of the above reasons.

Claim 7 requires “an insulating film is provided for insulating said bonding pad from other wirings than the predetermined wiring among said plurality of wirings, and wherein said insulating film is formed over said other wirings so as to directly contact the bonding pad.”

Chittipeddi fails to disclose or suggest these features of claim 7. First, Chittipeddi’s insulating film 3 is not provided “over” the alleged other wirings 19 as required by claim 7. Second, Chittipeddi’s insulating film 3 is not provided for insulating the alleged bonding pad 17 from the other wirings 19 as required by claim 7.

Claim 11 requires “an insulating film is provided for insulating said bonding pad from other wirings than the predetermined wiring among said plurality of wirings, and wherein said insulating film is formed above said other wirings so as to directly contact the bonding pad.” For example and without limitation, Fig. 6 of the instant application illustrates that insulating film 5 is provided above the other wirings 12 so as to insulating them from the bonding pad 1.

Chittipeddi fails to disclose or suggest these features of claim 11. Chittipeddi’s insulating film 3 is not provided “above” the alleged other wirings 19 as required by claim 11. Moreover, Chittipeddi’s insulating film 3 is not provided for insulating the alleged bonding pad 17 from the other wirings 19 as required by claim 11.

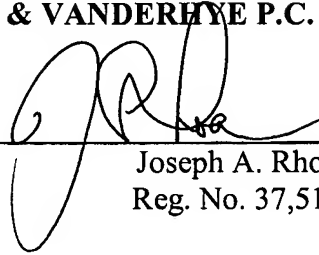
It is requested that all rejections be withdrawn. All claims are in condition for allowance. If any minor matter remains to be resolved, the Examiner is invited to telephone the undersigned with regard to the same.

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Respectfully submitted,

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